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## NPN MEDIUM POWER SILICON **TRANSISTOR**

Qualified per MIL-PRF-19500/393

Qualified Levels: JAN, JANTX and **JANTXV** 

## **DESCRIPTION**

This family of high-frequency, epitaxial planar transistors feature low saturation voltage. These devices are also available in TO-5 and low profile U4 packages. Microsemi also offers numerous other transistor products to meet higher and lower power ratings with various switching speed requirements in both through-hole and surface-mount packages.

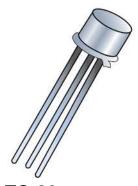
**Important:** For the latest information, visit our website <a href="http://www.microsemi.com">http://www.microsemi.com</a>.

## **FEATURES**

- JEDEC registered 2N3418 through 2N3421 series.
- JAN, JANTX, and JANTXV qualifications are available per MIL-PRF-19500/393.
- RoHS compliant versions available (commercial grade only).
- $V_{CE(sat)} = 0.25 V @ Ic = 1 A.$
- Rise time  $t_r = 0.22 \,\mu s \, max \, @ \, I_C = 1.0 \, A, \, I_{B1} = 100 \, mA.$
- Fall time  $t_f = 0.20 \,\mu s \, max \, @ \, I_C = 1.0 \, A, \, I_{B2} = -10 \, 0 \, mA.$

## **APPLICATIONS / BENEFITS**

- General purpose transistors for medium power applications requiring high frequency switching and low package profile.
- Military and other high-reliability applications.



**TO-39** (TO-205AD) **Package** 

## Also available in:

TO-5 package (leaded) **1 2N3418 – 2N3421** 

U4 package (surface mount) 2N3418U4 – 2N3421U4

## **MAXIMUM RATINGS**

Parameters / Test Conditions	Symbol	2N3418S 2N3420S	2N3419S 2N3421S	Unit
Collector-Emitter Voltage	$V_{CEO}$	60	80	V
Collector-Base Voltage	V <sub>CBO</sub>	85 125		V
Emitter-Base Voltage	$V_{EBO}$	8		V
Collector Current tp <= 1 ms, duty cycle <= 50%	Ic	3 5		Α
Total Power Dissipation @ $T_A = +25  ^{\circ}\text{C}^{(1)}$ @ $T_C = +100  ^{\circ}\text{C}^{(2)}$	P <sub>D</sub>	1 5		W
Operating & Storage Junction Temperature Range	$T_J, T_{stg}$	-65 to	+200	°C

- **Notes:** 1. Derate linearly 5.72 mW/ $^{\circ}$ C for  $T_A > +25 ^{\circ}$ C.
  - 2. Derate linearly 150 mW/°C for  $T_C > +100$  °C.

## MSC - Lawrence

6 Lake Street, Lawrence, MA 01841 Tel: 1-800-446-1158 or (978) 620-2600 Fax: (978) 689-0803

## MSC - Ireland

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#### Website:

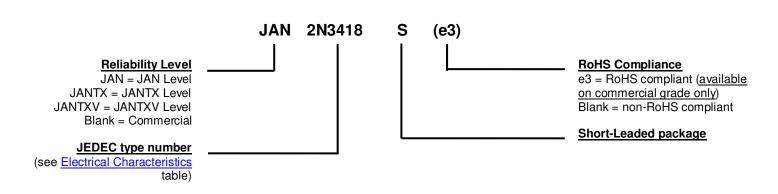
www.microsemi.com



## **MECHANICAL and PACKAGING**

- CASE: Hermetically sealed, kovar base, nickel cap.
- MARKING: Part number, date code, manufacturer's ID.
- POLARITY: See <u>Package Dimensions</u> on last page.

## PART NOMENCLATURE



	SYMBOLS & DEFINITIONS					
Symbol	Definition					
C <sub>obo</sub>	Common-base open-circuit output capacitance.					
I <sub>CEO</sub>	Collector cutoff current, base open.					
I <sub>CEX</sub>	Collector cutoff current, circuit between base and emitter.					
I <sub>EBO</sub>	Emitter cutoff current, collector open.					
h <sub>FE</sub>	Common-emitter static forward current transfer ratio.					
T <sub>A</sub>	Ambient temperature, free-air temperature.					
$V_{\sf CEO}$	Collector-emitter voltage, base open.					
$V_{CBO}$	Collector-emitter voltage, emitter open.					
$V_{EBO}$	Emitter-base voltage, collector open.					



## **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = +25°C, unless otherwise noted)

## **OFF CHARACTERISTICS**

Parameters / Test Conditions	Symbol	Min.	Max.	Unit	
Collector-Emitter Breakdown Cu	ırrent				
$I_C = 50 \text{ mA}, I_B = 0$	2N3418S, 2N3420S 2N3419S, 2N3421S	V <sub>(BR)CEO</sub>	60 80		V
Collector-Emitter Cutoff Current					
$V_{BE} = -0.5 \text{ V}, V_{CE} = 80 \text{ V}$ $V_{BE} = -0.5 \text{ V}, V_{CE} = 120 \text{ V}$	2N3418S, 2N3420S 2N3419S, 2N3421S	I <sub>CEX</sub>		0.3 0.3	μΑ
Collector-Base Cutoff Current $V_{CE} = 45 \text{ V}, I_B = 0$ $V_{CE} = 60 \text{ V}, I_B = 0$	2N3418S, 2N3420S 2N3419S, 2N3421S	I <sub>CEO</sub>		5.0 5.0	μА
Emitter-Base Cutoff Current $V_{EB} = 6.0 \text{ V}, I_C = 0$ $V_{EB} = 8.0 \text{ V}, I_C = 0$		I <sub>EBO</sub>		0.5 10	μΑ

## ON CHARACTERISTICS (1)

Parameters / Test Conditions		Symbol	Min.	Max.	Unit	
Forward-Current Transfer Ratio						
$I_{C} = 100 \text{ mA}, V_{CE} = 2.0 \text{ V}$	2N3418S, 2N3419S 2N3420S, 2N3421S		20 40			
$I_{C} = 1.0 \text{ A}, V_{CE} = 2.0 \text{ V}$	2N3418S, 2N3419S 2N3420S, 2N3421S	h <sub>FF</sub>	20 40	60 120		
$I_C = 2.0 \text{ A}, V_{CE} = 2.0 \text{ V}$	2N3418S, 2N3419S 2N3420S, 2N3421S		15 30			
$I_{C} = 5.0 \text{ A}, V_{CE} = 5.0 \text{ V}$	2N3418S, 2N3419S 2N3420S, 2N3421S		10 15			
Collector-Emitter Saturation Voltage						
$I_{C} = 1.0 \text{ A}, I_{B} = 0.1 \text{ A}$ $I_{C} = 2.0 \text{ A}, I_{B} = 0.2 \text{ A}$		$V_{CE(sat)}$		0.25 0.5	V	
Base-Emitter Saturation Voltage $I_C = 1.0 \text{ A}, I_B = 0.1 \text{ A}$		$V_{BE(sat)}$	0.6	1.2	٧	
$I_C = 2.0 \text{ A}, I_B = 0.2 \text{ A}$			0.7	1.4		

## **DYNAMIC CHARACTERISTICS**

Parameters / Test Conditions	Symbol	Min.	Max.	Unit
Magnitude of Common Emitter Small-Signal Short Circuit Forward Current Transfer Ratio $I_{C}=0.1\ A,\ V_{CE}=10\ V,\ f=20\ MHz$	h <sub>fe</sub>	1.3	0.8	
Output Capacitance $V_{CB} = 10 \text{ V}, I_E = 0, 100 \text{ kHz} \le f \le 1.0 \text{ MHz}$	$C_obo$		150	pF

NOTES: (1) Pulse Test: Pulse Width = 300  $\mu s,$  Duty Cycle  $\leq$  2.0%.



## ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = +25°C, unless otherwise noted) continued

## **SWITCHING CHARACTERISTICS**

Parameters / Test C	conditions (for all symbols)	Symbol	Min.	Max.	Unit
Delay Time Rise Time	$V_{BE(off)} = -3.7 \text{ V},$ $I_{C} = 1.0 \text{ A}, I_{B1} = 100 \text{ mA}$	t <sub>d</sub> t <sub>r</sub>		0.08 0.22	μs
Storage Time Fall Time	$V_{BE(off)} = -3.7 \text{ V},$ $I_{C} = 1.0 \text{ A}, I_{B2} = -100 \text{ mA}$	t <sub>s</sub> t <sub>f</sub>		1.10 0.20	μs
Turn-Off Time	$V_{BE(off)} = -3.7 \text{ V}, I_C = 1.0 \text{ A}, I_{B2} = -100 \text{ mA}, R_L = 20 \Omega$	t <sub>off</sub>		1.20	μs

## SAFE OPERATING AREA (See graph below and reference MIL-STD-750, method 3053)

DC Test

 $T_C = +100 \, ^{\circ}\text{C}$ , 1 cycle,  $t \ge 1.0 \, \text{s}$ 

Test 1

 $V_{CE} = 5.0 \text{ V}, I_{C} = 3.0 \text{ A}$ 

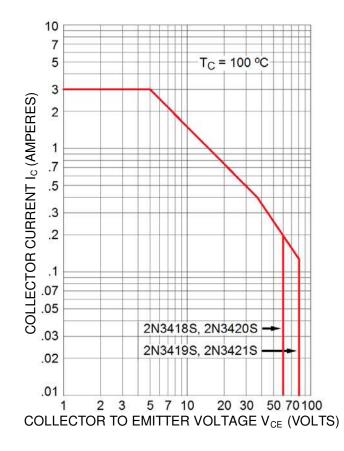
Test 2

 $V_{CE} = 37 \text{ V}, I_{C} = 0.4 \text{ A}$ 

Test 3

 $V_{CE} = 60 \text{ V}, I_{C} = 0.185 \text{ A}$  2N3418S, 2N3420S  $V_{CE} = 80 \text{ V}, I_{C} = 0.12 \text{ A}$  2N3419S, 2N3421S

Clamped Switching  $T_A = +25 \, ^{\circ}\text{C}, I_B = 0.5 \, \text{A}, I_C = 3.0 \, \text{A}$ 



Maximum Safe Operating Area (continuous dc)



## **GRAPHS**

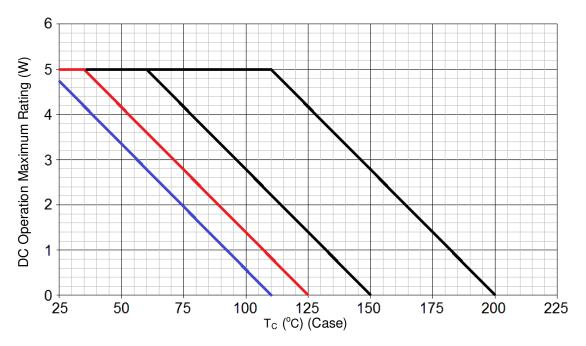


FIGURE 1

**Temperature-Power Derating Curve** 

NOTES: Thermal Resistance Junction to Case = 4.5 °C/W Max Finish-Alloy Temp = 175.0 °C

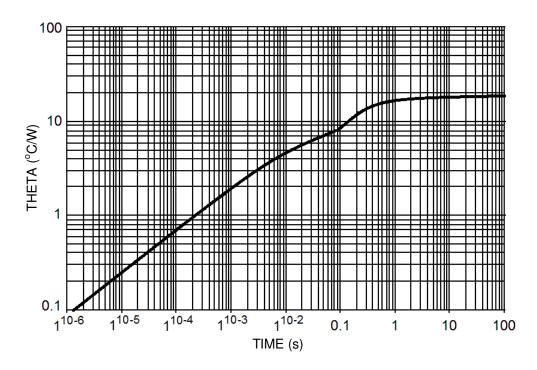


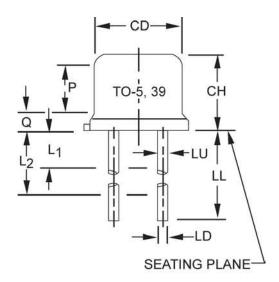
FIGURE 2

Maximum Thermal Impedance

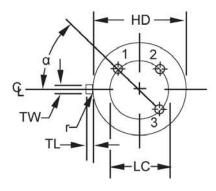
**NOTE:**  $T_C = +25$  °C, Thermal Resistance  $R_{\theta JC} = 4.5$  °C/W



## **PACKAGE DIMENSIONS**



Dimensions					
Symbol	Inc	hes	Millimeters		Note
	Min	Max	Min	Max	
CD	.305	.335	7.75	8.51	
CH	.240	.260	6.10	6.60	
HD	.335	.370	8.51	9.40	
LC	.200	TP	5.08	TP	6
LD	.016	.021	0.41	0.53	
LL	.500	.750	12.7	19.05	7
LU	See notes 7, 13, 14				
L <sub>1</sub>		.050		1.27	7
L <sub>2</sub>	.250		6.35		7
Р	.100		2.54		5
Q		.040		1.02	4
TL	.029	.045	0.74	1.14	3, 10
TW	.028	.034	0.71	.86	9, 10
r		.010		0.25	11
α	45°	TP	45°	TP	6



- 1. Dimensions are in inches.
- 2. Millimeters are given for general information only.
- 3. Symbol TL is measured from HD maximum.
- 4. Details of outline in this zone are optional.
- 5. Symbol CD shall not vary more than .010 inch (0.25 mm) in zone P. This zone is controlled for automatic handling.
- 6. Leads at gauge plane .054 inch (1.37 mm) +.001 inch (0.03 mm) -.000 inch (0.00 mm) below seating plane shall be within .007 inch (0.18 mm) radius of TP relative to tab. Device may be measured by direct methods or by gauge.
- 7. Symbol LU applies between L1 and L2. Dimension LD applies between L2 and LL minimum. Diameter is uncontrolled in L1 and beyond LL minimum.
- 8. Lead number 3 is electrically connected to case.
- 9. Beyond r maximum, TW shall be held for a minimum length of .021 inch (0.53 mm).
- 10. Lead number 4 omitted on this variation.
- 11. Symbol r applied to both inside corners of tab.
- 12. For transistor types 2N3418S, 2N3419S, 2N3420S, 2N3421S, LL is .500 (12.70 mm) minimum and .750 (19.05 mm) maximum.
- 13. In accordance with ASME Y14.5M, diameters are equivalent to  $\Phi x$  symbology.
- 14. Lead 1 is emitter, lead 2 is base, and lead 3 is collector.